

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15360
1.3 Title of PCN	STM32MP23x & STM32MP25x - Product enhancement
1.4 Product Category	STM32MP257x STM32MP255x STM32MP253x STM32MP251x STM32MP235x STM32MP233x STM32MP231x
1.5 Issue date	2025-09-16

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
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2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.2.2 Marketing Manager	Veronique BARLATIER
2.2.3 Quality Manager	Pascal NARCHE

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC FAB14 (Taiwan)

### 4. Description of change

	Old	New
4.1 Description	Current STM32MP23x and STM32MP25x (Die 505 - cut2.1 -Revision Y) product has limitations described in Errata Sheet ES0598 - Rev 4 - April 2025	New STM32MP23x and STM32MP25x (Die 505 - cut2.2 - Revision X) product enhancement fixes some limitations: - ETH1 RMII timing violation solved - ROM code: Standby modes support in Secured_Locked state - ROM code: illegal access error correction during DStandby exit in M33-TD mode - VBAT TAMPER architecture robustness improvement to avoid disturbing LSE in case of negative current injection on VSW. Details are described in Errata Sheet ES0598 - Rev 5 - August 2025
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

### 5. Reason / motivation for change

5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE CONTINUITY

### 6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "Y" to "X" on Package Marking
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### 7. Timing / schedule

7.1 Date of qualification results	2025-10-30
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7.2 Intended start of delivery	2025-09-30
7.3 Qualification sample available?	Upon Request

#### 8. Qualification / Validation

8.1 Description	15360 MDG-GPAM RER2018 - PCN15360 STM32MP23x STM32MP25x - Die 505_X cut2.2 - Rel plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-09-16

#### 9. Attachments (additional documentations)

15360 Public product.pdf  
 15360 MDG-GPAM RER2018 - PCN15360 STM32MP23x STM32MP25x - Die 505\_X cut2.2 - Rel plan.pdf  
 15360 \_Additional information.pdf

#### 10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32MP235DAK3	
	STM32MP235DAL3	
	STM32MP235FAK3	
	STM32MP235FAL3	
	STM32MP251AAK3	
	STM32MP253CAI3	
	STM32MP253CAL3	
	STM32MP255CAL3	
	STM32MP255DAK3	
	STM32MP255DAL3	
	STM32MP255FAI3	
	STM32MP255FAK3	
	STM32MP257CAI3	
	STM32MP257DAI3	
	STM32MP257DAK3	
	STM32MP257DAL3	
	STM32MP257FAI3	
	STM32MP257FAK3	
	STM32MP257FAL3	

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